Docket No. NDMENT TRANSMITTAL LETTER M4065.0477/P477 Application No. Filing Date Examiner Art Unit 09/939,636-Conf. #4394 August 28, 2001 J. Nguyen 2815 Applicant(s): Kevin M. Devereaux METHOD AND APPARATUS FOR WAFER LEVEL TESTING OF SEMICONDUCTOR Invention: USING SACRIFICIAL ON DIE POWER AND GROUND METALIZATION TO THE COMMISSIONER FOR PATENTS Transmitted herewith is an amendment in the above-identified application. The fee has been calculated and is transmitted as shown below. **CLAIMS AS AMENDED** Claims Highest Remaining Number Number After Previously **Extra Claims** Amendment Paid Present Rate **Total Claims** 19 24 Х 0.00 Independent 3 3 0.00 х Claims Multiple Dependent Claims (check if applicable) Other fee (please specify): TOTAL ADDITIONAL FEE FOR THIS AMENDMENT: 00.00 x | Large Entity Small Entity x No additional fee is required for this amendment. Please charge Deposit Account No. in the amount of \$ A duplicate copy of this sheet is enclosed. A check in the amount of \$ to cover the filing fee is enclosed. Payment by credit card. Form PTO-2038 is attached. × The Director is hereby authorized to charge and credit Deposit Account No. as described below. A duplicate copy of this sheet is enclosed. x Credit any overpayment. Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17. Dated: June 4, 2003

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(PATENT)

(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Kevin M. Devereaux

Application No.: 09/939,636

Group Art Unit: 2815

Filed: August 28, 2001

Examiner: J. Nguyen

For: METHOD AND APPARATUS FOR WAFER LEVEL TESTING OF SEMICONDUCTOR USING SACRIFICIAL ON DIE POWER AND GROUND METALIZATION

AMENDMENT UNDER 37 C.F.R. 1.116, REQUEST FOR RECONSIDERATION AND REQUEST FOR WITHDRAWL OF FINAL REJECTION STATUS

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Commissioner for Patents Washington, DC 20231

Dear Sir:

In response to the Office Action dated March 4, 2003 (Paper No. 10) Finally rejecting claims 1-11 and 25-32, please amend the above-identified U.S. patent application as follows:

In the Claims

Please rewrite claim 1, 9, 10 and 25 as follows:

1. (Currently Amended) A semiconductor wafer comprising:

at least one first sacrificial conductive line for supplying a first voltage to a plurality of dies fabricated on said wafer;